ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16600

Generic Copy

Issue Date: 19-May-2011

TITLE: Final Notification for Transfer of Phos Zener Filtering products from Hynix (Magna Chip) in Korea to ON Semiconductor Pocatello (ID).

PROPOSED FIRST SHIP DATE: 19-Aug-2011

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

AFFECTED PRODUCT DIVISION: Standard Products

FOR SAMPLES: Contact your local ON Semiconductor Sales Office

FOR ANY QUESTIONS CONCERNING RELIABILITY DATA: Contact your local ON Semiconductor Sales Office or Francis Lualhati < Francis.Lualhati@onsemi.com>

CHANGE FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customers of its plan to transfer fabrication of phosphorous zener EMI filter products from Hynix (Magna Chip) located in Seoul, South Korea, to ON Semiconductor Fab 10 located in Pocatello, ID (USA).

Description of the change:

The transfer and qualification of the Phosphorous Zener processes and the associated integrated circuits from the Hynix (Magna Chip) facility (South Korea) to the Fab 10 wafer fabrication site located in the Pocatello, Idaho.

The Fab 10 facility is an ON Semiconductor owned wafer fab that has been producing products since 2000 (formerly as AMI). Several existing technologies within ON Semiconductor's product families are currently sourced from Fab 10, including CMOS and LVFR products The Fab 10 Pocatello site is certified according to ISO9001:2008, 14001:2004, ISO/TS 16949:2009 and AS 9100B standards as well as MIL_PRF-38535, CTPAT and STACK.

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Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

Devices listed in this final PCN should be transferred to ON Semiconductor Fab 10 in Pocatello starting June 2011. After 20 July 2011, customer may receive devices from either facility. Parts are identifiable by date code 1129 (YYWW).

QUALIFICATION PLAN

Product Qualification Vehicles

Reliability testing was performed on qualification vehicles chosen based on die size, voltage rating, and run rates. The following qualification vehicles were selected for this qualification.

RELIABILITY DATA SUMMARY:

Reliability Test Results for CM1442-08CP:

Test:	**Conditions:**	**Interval:**	**Results**		
HTRB	TA = 125°C, bias=80% rated V or100V Max	1008 hrs	0/80	0/80	0/80
HTSL	Ta=150°C	1008 hrs	0/80	0/80	0/80
UHAST	Ta=130°C, RH=85%	96 hrs	0/80	0/80	0/80
TC	Ta= -40/125°C	1000 cyc	0/80	0/80	0/80
AC	Ta=+121°C, RH=100%, P=15psig,	96 hrs	0/80	0/80	0/80
CDPA	After Post TC		0/3	0/3	0/3

ELECTRICAL CHARACTERIZATION RESULTS:

Available upon request

CHANGED PART IDENTIFICATION

There will be no changes to standard device markings. Normal assembly lot traceability codes will identify the wafer fab source.

AFFECTED DEVICE LIST

CM1442-08CP
CM1422-03CP
CM1442-06CP
CM1442-06LP